

ASMNUT.124C1



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Basol et al.
Appl. No. : 10/663,318
Filed : September 16, 2003
For : CONDUCTIVE STRUCTURE
FABRICATION PROCESS USING
NOVEL LAYERED STRUCTURE
AND CONDUCTIVE
STRUCTURE FABRICATED
THEREBY FOR USE IN MULTI-
LEVEL METALLIZATION
Examiner : Thao X. Le
Group Art Unit : 2814

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

February 24, 2005

(Date)

A handwritten signature in black ink, appearing to read "Adeel Syed Akhtar".

Adeel S. Akhtar, Reg. No. 41,394

RESPONSE TO OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed on November 29, 2004, please amend the above-captioned application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.